

## SLVU2.8-4

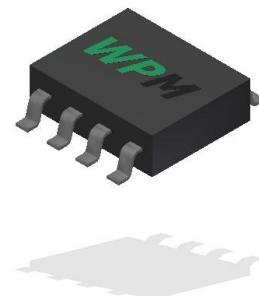
### Low Capacitance TVS Array for Surge & ESD Protection

The SLVU2.8-4 has a low typical capacitance of 1.5pF and operates with virtually no insertion loss to 1GHz. The SLVU2.8-4 is in an SOP-8 package and may be used to protect two high-speed line pairs. This makes the device ideal for protection of data lines such as 10/100M Ethernet, gigabit Ethernet interfaces. It may be used to meet the ESD immunity requirements of IEC61000-4-2, Level 4 ( $\pm 15\text{kV}$  air,  $\pm 8\text{kV}$  contact discharge).

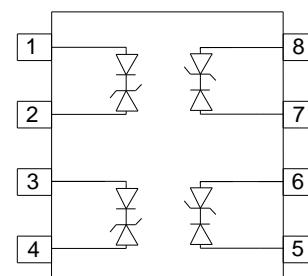
It has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events),and lightning.

#### Features

- 600 Watts peak pulse power ( $tp = 8/20\mu\text{s}$ )
- Protects two line pairs (four lines)
- Low capacitance
- Working voltages : 2.8V
- Low leakage current
- Response Time is < 1 ns
- Low capacitance (<3.0pF) for high-speed interfaces
- Meets MSL 1 Requirements
- Solid-state silicon avalanche technology
- ROHS compliant
- WeiPan technology



**SOP-8**



#### Main applications

- 10/100/1000 Ethernet
- WAN/LAN Equipment
- Switching Systems
- Instrumentation
- Base Stations
- Analog Inputs

#### Protection solution to meet

- IEC61000-4-2 (ESD)  $\pm 15\text{kV}$  (air),  $\pm 8\text{kV}$  (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 25A (8/20 $\mu\text{s}$ )

#### Ordering Information

Device	Qty per Reel	Reel Size
SLVU2.8-4	2500	13 Inch

**Maximum ratings (Tamb=25°C Unless Otherwise Specified)**

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P <sub>PPP</sub>	600	Watts
Peak Pulse Current(tp=8/20μs waveform)	I <sub>PP</sub>	25	A
ESD Rating per IEC61000-4-2:			
Contact		8	KV
Air		15	
Lead Soldering Temperature	T <sub>L</sub>	260 (10 sec.)	°C
Operating Temperature Range	T <sub>J</sub>	-55 ~ 150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ 150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

\*Other voltages may be available upon request.

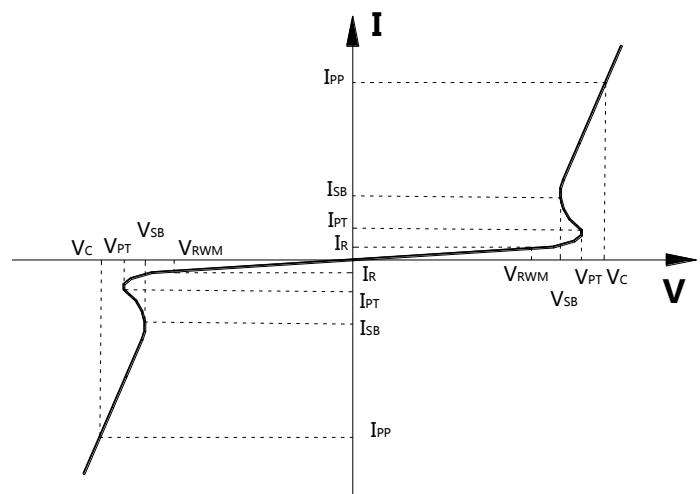
1. Non-repetitive current pulse, per Figure 1.

**Electrical characteristics ( Tamb=25°C Unless Otherwise Specified)**

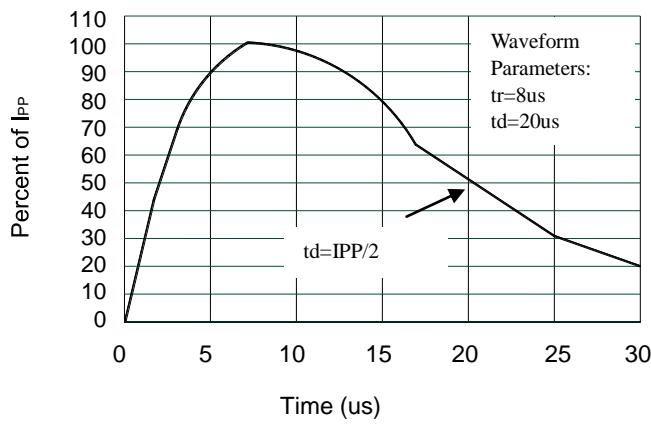
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
V <sub>RWM</sub>	Reverse Working Voltage				2.8	V
V <sub>PT</sub>	Punch-Through Voltage	I <sub>PT</sub> = 2μA, (Each Line)	3.0			V
V <sub>SB</sub>	Snap-Back Voltage	I <sub>SB</sub> = 50mA, (Each Line)	2.8			
I <sub>R</sub>	Reverse Leakage Current	V <sub>RWM</sub> = 2.8V, (Each Line)			1	μA
V <sub>C</sub>	Clamping Voltage	I <sub>PP</sub> = 1A, tp = 8/20μs, (Each Line)			7.6	V
		I <sub>PP</sub> = 24A, tp = 8/20μs, (Each Line)			25	V
I <sub>PP</sub>	Peak Pulse Current	tp = 8/20μs(Each Line)			25	A
C <sub>J</sub>	Junction Capacitance	V <sub>R</sub> = 0V, f = 1MHz, (Each Line)		1.5	3.0.	pF

Junction capacitance is measured in VR=0V,F=1MHz

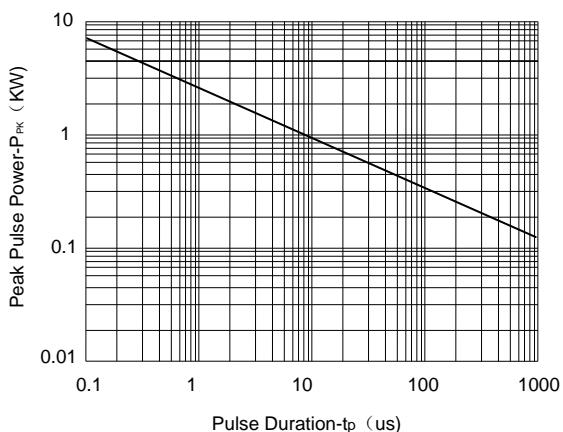
Symbol	Parameter
V <sub>RWM</sub>	Working Peak Reverse Voltage
V <sub>PT</sub>	Punch-Through Voltage@ I <sub>PT</sub>
V <sub>SB</sub>	Snap-Back Voltage@ I <sub>SB</sub>
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
I <sub>T</sub>	Test Current
I <sub>RM</sub>	Leakage current at V <sub>RWM</sub>
I <sub>PP</sub>	Peak pulse current
C <sub>O</sub>	Off-state Capacitance
C <sub>J</sub>	Junction Capacitance



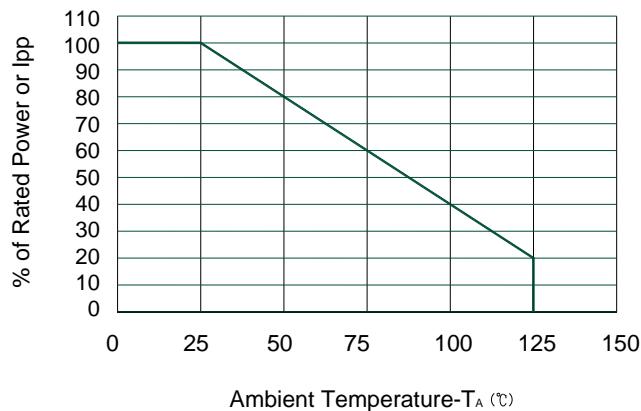
### Typical electrical characterist applications



Pulse Waveform

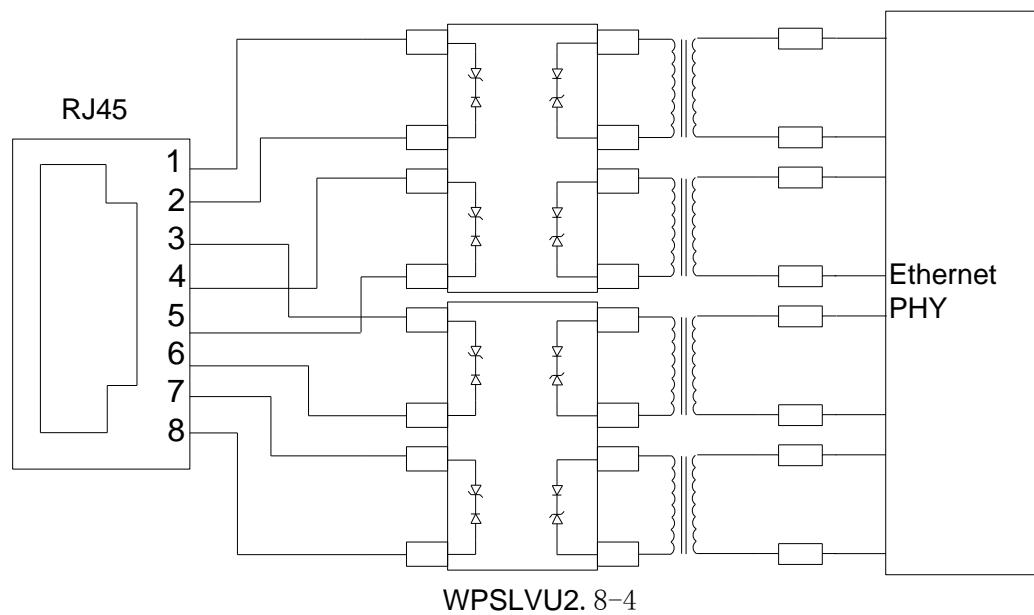


Non-Repetitive Peak Pulse Power vs. Pulse Time

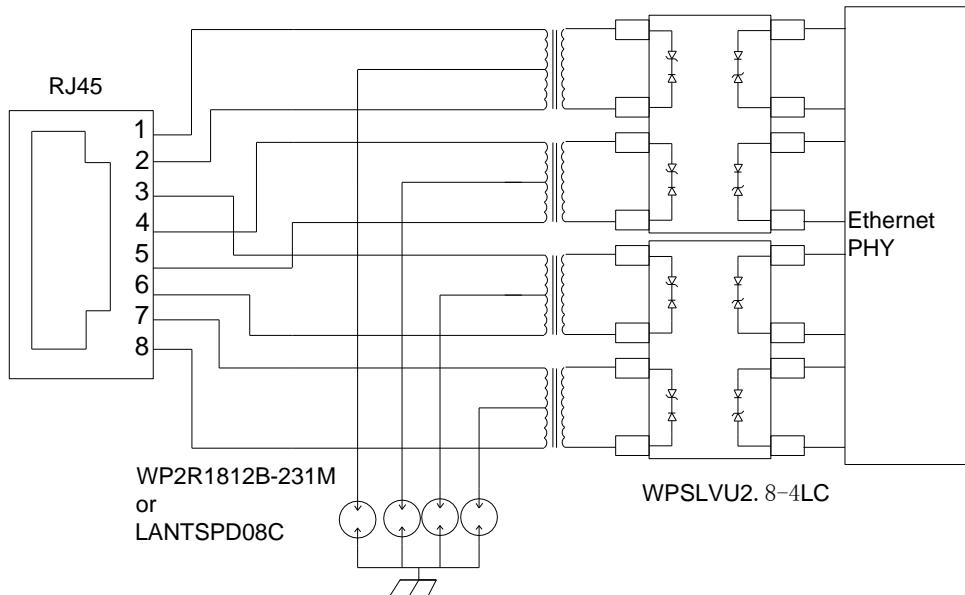


Power Derating Curve

### Typical applications



**Surge protection for Ethernet**



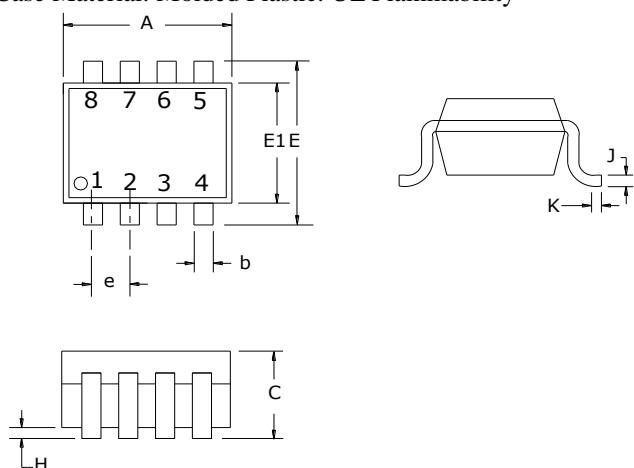
## Package Information

### SOP-8

#### Mechanical Data

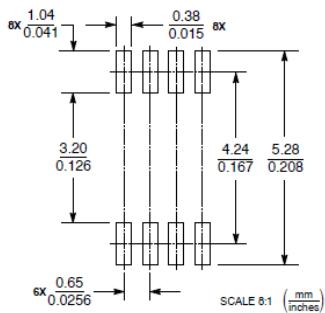
Case: SOP-8

Case Material: Molded Plastic. UL Flammability

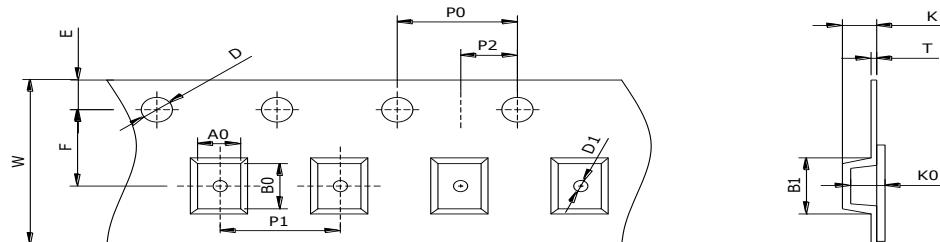


DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	4.80	5.00	0.189	0.197
E	6.00(BSC)			0.236(BSC)
E1	3.80	4.00	0.150	0.157
b	0.33	0.51	0.013	0.020
C	1.35	1.75	0.053	0.069
J	0.17	0.25	0.007	0.010
e	1.27(BSC)			0.05(BSC)
K	0.40	1.27	0.016	0.050
H	0.10	0.25	0.004	0.010

#### Recommended Pad outline



#### SOP-8 Reel Dim



Package	Chip Size (mm)	Pocket Size B0×A0×K0(mm)	Tape Width	Reel Diameter	Quantity Per Reel	P0	P1
SOP-8	6.0×5.0×1.50	6.20×5.20×1.70	12mm	330mm(13")	2500	8mm	8mm
D0	D1	E	F	K	T	W	
1.5mm	1.5mm	1.75mm	5.0mm	1.55mm	0.20mm	12mm	